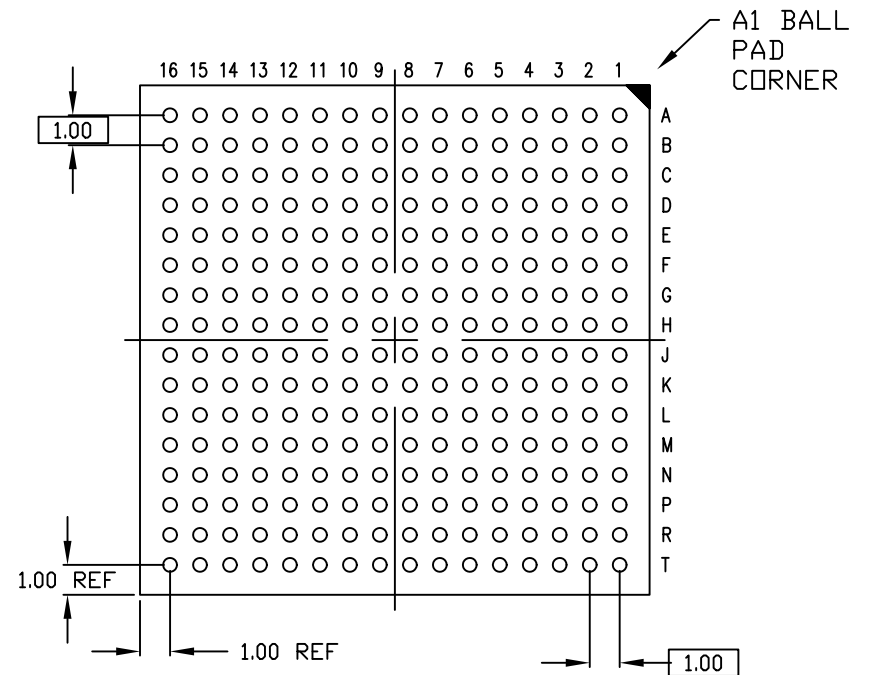
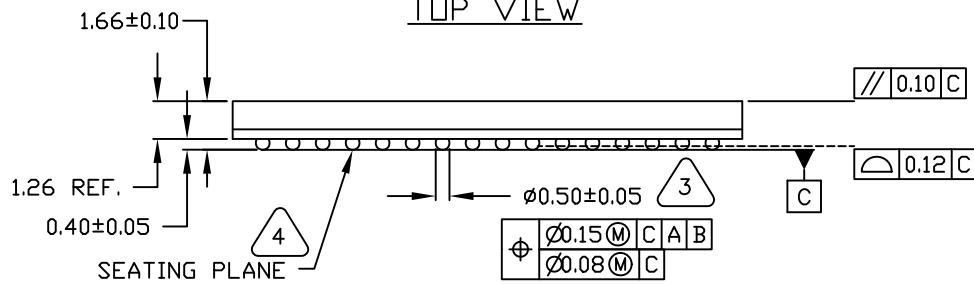


TOP VIEW



BOTTOM VIEW
(BALL SIDE)



SIDE VIEW

PKG. CODE: X256-3

NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
- ③ DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- ④ PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- ⑤ A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131.
8. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbfREE (+) PKG. CODES.



TITLE: PACKAGE OUTLINE, 256 BALLS CSBGA, 17x17mm, 4 LAYER, 1.00mm PITCH			
APPROVAL	DOCUMENT CONTROL NO. 21-0499	REV. A	1/1

-DRAWING NOT TO SCALE-